



# SOT1168-1

plastic, thermal enhanced ultra thin small outline package; 16 terminals; 0.4 mm pitch; 3.3 mm x 1.35 mm x 0.55 mm body

30 January 2017

Package information

## 1. Package summary

Terminal position code	D (double)
Package type descriptive code	HUSON6
Package type industry code	DFN3314-16
Package style descriptive code	HUSON (thermal enhanced ultra thin small outline; no leads)
Package body material type	P (plastic)
IEC package outline code	- - -
JEDEC package outline code	- - -
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	22-3-2010
Manufacturer package code	SOT1168

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.2	-	3.3	3.4	mm
E	package width	1.25	-	1.35	1.45	mm
A	seated height	-	-	-	0.55	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	16	-	

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## 2. Package outline

HUSON16: plastic, thermal enhanced ultra thin small outline package; no leads; 16 terminals; body 1.35 x 3.3 x 0.55 mm

SOT1168-1

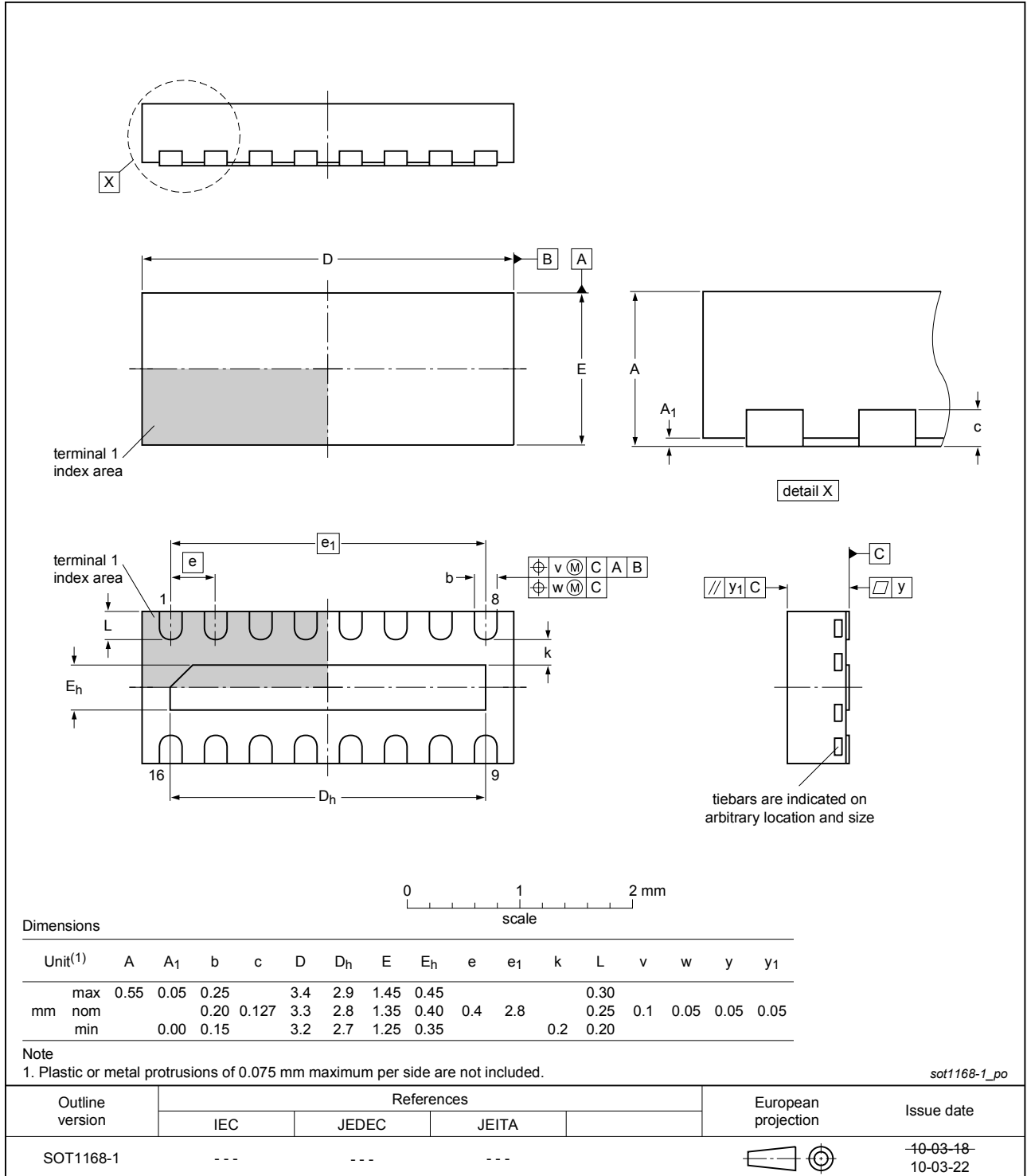


Fig. 1. Package outline DFN3314-16 (SOT1168-1)

plastic, thermal enhanced ultra thin small outline package; 16 terminals; 0.4 mm pitch; 3.3 mm x 1.35 mm x 0.55 mm body

### 3. Soldering

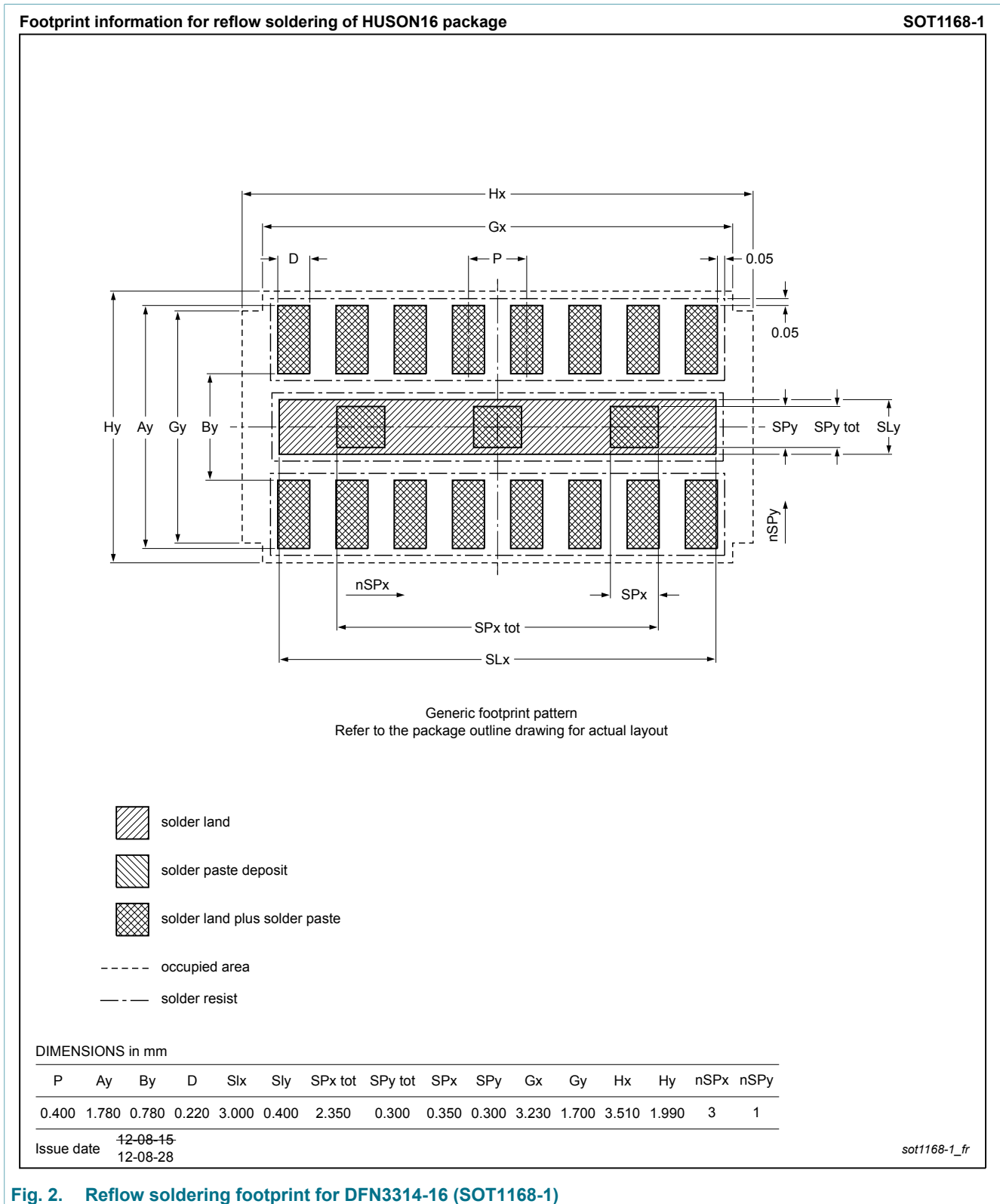


Fig. 2. Reflow soldering footprint for DFN3314-16 (SOT1168-1)

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## 4. Legal information

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